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 Ref No. : H13-D454-0021
 Date : April 15, 2013

Att: _____

PROCESS CHANGE NOTICE

Regarding Photocouplers (S06 Packing Specification)

We appreciate your continued patronage of our semiconductor products.
 The following changes are planned regarding photocouplers. Please kindly review the contents. We would appreciate your understanding.

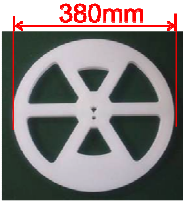
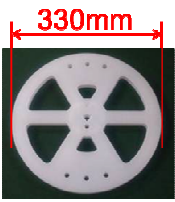
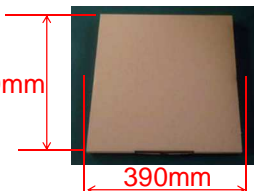
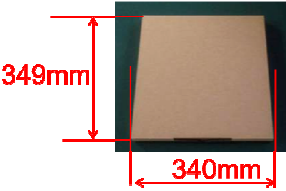
1. Affected products

The following products, including customer-specific products and (TST) products.

TLP104(*.E(X	TLP109(*.E(X	TLP116A(*.E(X	TLP118(*.E(X	TLP151A(*.E(X
TLP151(*.E(X	TLP152(*.E(X	TLP155(*.E(X	TLP155(*.F(X	TLP2309(*.E(X
TLP2355(*.E(X	TLP2358(*.E(X	TLP184(*.SE(X	TLP185(*.SE(X	TLP184(*.(X
TLP185(*.(X				

X:J,OorT

2. Changes

Changes		Pre-Change	Post-Change
1)	Diameter of tape reel	Reel diameter : 380 mmφ 	Reel diameter : 330 mmφ 
2)	Carton size	390 x 390 x 28 mm 	340 x 349 x 31 mm 

3. Reason for the change

- Production control improvement by integrating the packing materials. 1) and 2)

4. Characteristics to be affected

As seen above, packing specifications are changed (diameter of tape reel, and carton size), but there is no change in the product design and manufacturing process. The product characteristics and reliability are the same as the existing product.

5. Date of the change

Change Item	Product	Date of Change
1)	TLP185(*,SE(T	From the production of May 2013
2)	The other products	From the production of June 2013

6. Request from Toshiba

If you have any question or inconvenience on this issue, please feel free to contact us through our sales representative before May 15, 2013.

Sincerely,



Megumi Shirahama / Manager
Optoelectronic Device Quality Assurance Group
Quality Assurance Department
Buzen Toshiba Electronics Corporation